

E-paper Display Series



GDEH075T90

Dalian Good Display Co., Ltd.



Product Specifications

| Customer | Standard |
|-------------|----------------------|
| Description | 7.5" E-PAPER DISPLAY |
| Model Name | GDEH075T90 |
| Date | 2020/05/26 |
| Revision | 1.0 |

| Design Engineering | | | | | | | |
|--------------------|-----------------------|----------|--|--|--|--|--|
| Approval | Approval Check Design | | | | | | |
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| Version | Content | Date | Producer |
|---------|-------------|------------|----------|
| 1.0 | New release | 2020/05/26 | |
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1. General Description

1.1 Overview

GDEH075T90 is an Active Matrix Electrophoretic Display (AMEPD), with interface and a reference system design. The 7.5" active area contains528×880 pixels, and has 1-bit B/W full display capabilities. An integrated circuit contains gate buffer, source buffer, interface, timing control logic, oscillator, DC-DC. SRAM.LUT, VCOM and border are supplied with each panel.

1.2 Features

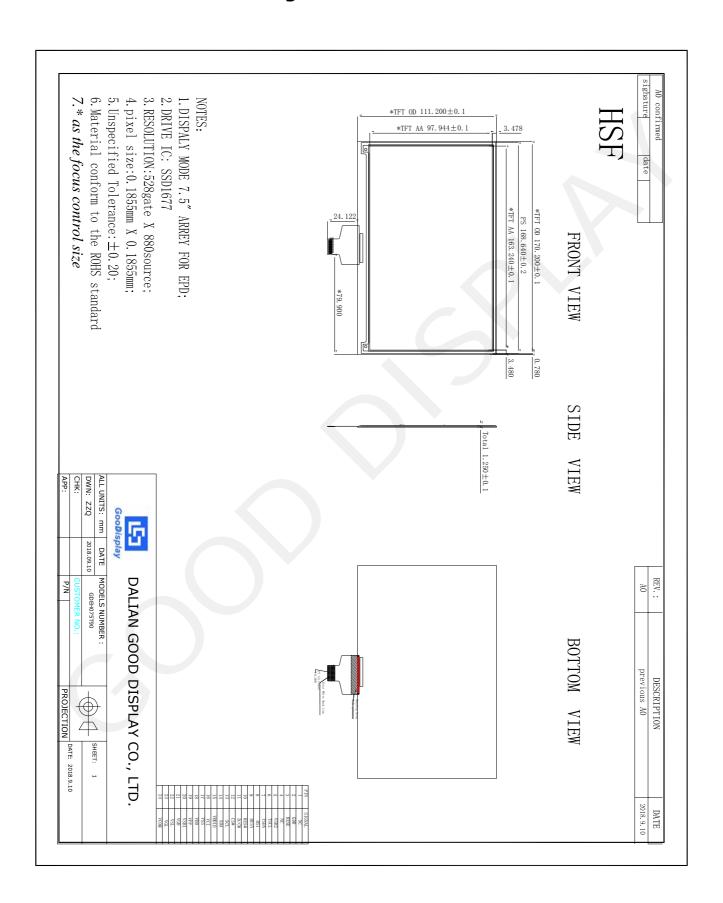
- 880x528 pixels display
- High contrast
- High reflectance
- Ultra wide viewing angle
- Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Commercial temperature range
- Landscape, portrait modes
- Hard-coat antiglare display surface
- Ultra Low current deep sleep mode
- On chip display RAM
- Low voltage detect for supply voltage
- High voltage ready detect for driving voltage
- Internal temperature sensor
- 10-byte OTP space for module identification
- Waveform stored in On-chip OTP
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I2C signal master interface to read external temperature sensor/built-in temperature sensor

1.3 Mechanical Specifications

| Parameter | Specifications | Unit | Remark |
|---------------------|----------------------------|-------|----------|
| Screen Size | 7.5 | Inch | |
| Display Resolution | 880(H)x528(V) | Pixel | Dpi: 137 |
| Active Area | 163.24(H)×97.94(V) | mm | |
| Pixel Pitch | 0.1855×0.1855 | mm | |
| Pixel Configuration | Rectangle | | |
| Outline Dimension | 170.2(H)×111.2 (V)x1.25(D) | mm | |
| Weight | 31±0.2 | g | |



1.4 Mechanical Drawing of EPD module





1.5 Input/Output Terminals

| Pin# | Single | Description | Remark |
|------|--------|--|------------|
| 1 | NC | No connection and do not connect with other NC pins | Keep Open |
| 2 | GDR | N-Channel MOSFET Gate Drive Control | |
| 3 | RESE | Current Sense Input for the Control Loop | |
| 4 | NC | No connection and do not connect with other NC pins e | Keep Open |
| 5 | VSH2 | Positive Source driving voltage | |
| 6 | TSCL | I2C Interface to digital temperature sensor Clock pin | |
| 7 | TSDA | I2C Interface to digital temperature sensor Date pin | |
| 8 | BS1 | Bus selection pin | Note 1.5-5 |
| 9 | BUSY | Busy state output pin | Note 1.5-4 |
| 10 | RES# | Reset | Note 1.5-3 |
| 11 | D/C # | Data /Command control pin | Note 1.5-2 |
| 12 | CS# | Chip Select input pin | Note 1.5-1 |
| 13 | SCL | serial clock pin (SPI) | |
| 14 | SDA | serial data pin (SPI) | |
| 15 | VDDIO | Power for interface logic pins | |
| 16 | VCI | Power Supply pin for the chip | |
| 17 | VSS | Ground | |
| 18 | VDD | Core logic power pin | |
| 19 | VPP | Power Supply for OTP Programming | |
| 20 | VSH1 | Positive Source driving voltage | |
| 21 | VGH | Power Supply pin for Positive Gate driving voltage and VSH | |
| 22 | VSL | Negative Source driving voltage | |
| 23 | VGL | Power Supply pin for Negative Gate driving voltage, VCOM and VSL | |
| 24 | VCOM | VCOM driving voltage | |

Note 1.5-1: This pin (CS#) is the chip select input connecting to the MCU. The chip is enabled for MCU communication: only when CS# is pulled LOW.

Note 1.5-2: This pin (D/C#) is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data will be interpreted as data. When the pin is pulled LOW, the data will be interpreted as command.

Note 1.5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 1.5-4: This pin (BUSY) is Busy state output pin. When Busy is High the operation of chip should not be

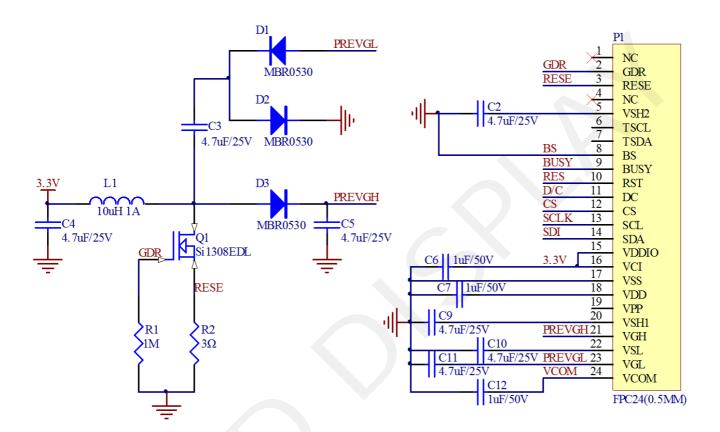
interrupted and any commands should not be issued to the module. The driver IC will put Busy pin High when the driver IC is working such as:

- Outputting display waveform; or
- Communicating with digital temperature sensor

Note 1.5-5: This pin (BS1) is for 3-line SPI or 4-line SPI selection. When it is "Low", 4-line SPI is selected. When it is "High", 3-line SPI (9 bits SPI) is selected.



1.6 Reference Circuit





1.7 Matched Development Kit

Our Development Kit designed for SPI E-paper Display aims to help users to learn how to use E-paper Display more easily. It can refresh black-white E-paper Display and three-color (black, white and red/Yellow) Good Display 's E-paper Display. And it is also added the functions of USB serial port, Raspberry Pi and LED indicator light ect.

DESPI Development Kit consists of the development board and the pinboard.

More details about the Development Kit, please click to the following link:

http://www.e-paper-display.com/products_detail/productId=402.html



2. Environmental

2.1 Handling, Safety and Environmental Requirements

WARNING

The display glass may break when it is dropped or bumped on a hard surface. Handle with care.

Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

CAUTION

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.

Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Data sheet status

Product specification | The data sheet contains final product specifications.

Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134).

Stress above one or more of the limiting values may cause permanent damage to the device.

These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and dose not form part of the specification.

| Product Environmental certification | 1 |
|-------------------------------------|---|
|-------------------------------------|---|

RoHS



2.2 Reliability test

| | TEST | CONDITION | METHOD | REMARK |
|----|---|--|--------------------------|--------|
| 1 | High-Temperature Operation | T=50°C RH=30%RH, For 240Hr | IEC 60 068-2-2Bb | |
| 2 | Low-Temperature Operation | T = 0°C for 240 hrs | IEC 60 068-2-2Ab | |
| 3 | High-Temperature Storage | T=70°C RH=40%RH For 240Hr Test in white pattern | IEC 60 068-2-2Bb | |
| 4 | Low-Temperature Storage | $T = -25^{\circ}C$ for 240 hrs Test in white pattern | IEC 60 068-2-2Ab | |
| 5 | High Temperature, High- Humidity Operation | T=40°C, RH=90%RH, For 168Hr | IEC 60 068-2-3CA | |
| 6 | High Temperature, High- Humidity Storage | T=60°C, RH=80%RH, For 240Hr Test in white pattern | IEC 60 068-2-3CA | |
| 7 | Temperature Cycle | -25°C(30min)~70°C(30min) , 100 Cycle Test in white pattern | IEC 60 068-2-14NB | |
| 8 | Package Vibration | 1.04G,Frequency: 10~500Hz Direction: X,Y,Z Duration:1hours in each direction | Full packed for shipment | |
| 9 | Package Drop Impact | Drop from height of 122 cm on Concrete surface Drop sequence:1 corner, 3edges, 6face One drop for each. | Full packed for shipment | |
| 10 | UV exposure Resistance | 765 W/m² for 168hrs,40°C | IEC 60068-2-5 Sa | |
| 11 | Electrostatic discharge | Machine model: +/-250V,0Ω,200pF | IEC61000-4-2 | |

Actual EMC level to be measured on customer application.

Note1: Stay white pattern for storage and non-operation test.

Note2: Operation is black/white/red pattern , hold time is 150S.

Note3: The function,appearence,opticals should meet the requirements of the test before and after the test. Note4: Keep testing after 2 hours placing at $20^{\circ}-25^{\circ}$.



3. ELECTRICAL CHARACTERISTICS

3.1 ABSOLUTE MAXIMUM RATING

Table 3.1-1: Maximum Ratings

| Symbol | Parameter | Rating | Unit |
|-----------|-----------------------------|--------------|--------------|
| V_{CI} | Logic supply voltage | -0.5 to +6.0 | V |
| T_{OPR} | Operation temperature range | 0 to 50 | C |
| T_{STG} | Storage temperature range | -25 to 60 | \mathbb{C} |
| - | Humidity range | 40~70 | %RH |

Note 1: Tstg is the transportation condition, the transport time is within 10 days for $-25\%\sim0\%$ or $50\%\sim60\%$.

Note 2: Avoid direct sunlight.

3.2 DC CHARACTERISTICS

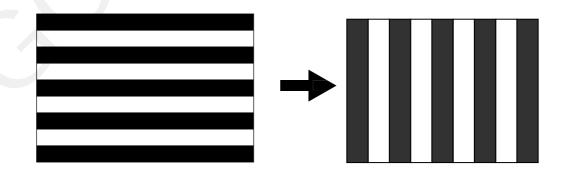
The following specifications apply for: VSS=0V, VCI=3.3V, T_{OPR}=25℃.

Table 3.2-1: DC Characteristics

| Symbol | Parameter | Test Condition | Applicable pin | Min. | Тур. | Max. | Unit |
|---------|---------------------------|-----------------------|----------------------|----------|------|----------|------|
| VCI | VCI operation voltage | - | VCI | 2.2 | 3 | 3.7 | V |
| VIH | High level input voltage | - | SDA, SCL, CS#, D/C#, | 0.8VDDIO | - | - | V |
| VIL | Low level input voltage | - | RES#, BS1 | - | - | 0.2VDDIO | V |
| VOH | High level output voltage | IOH = -100uA | BUSY, | 0.9VDDIO | - | - | V |
| VOL | Low level output voltage | IOL = 100uA | | - | - | 0.1VDDIO | V |
| Iupdate | Module operating current | - | - | - | | 18 | mA |
| Isleep | Deep sleep mode | VCI=3.3V | - | - | | 2 | uA |

- The Typical power consumption is measured using associated 25° C waveform with following pattern transition: from horizontal scan pattern to vertical scan pattern. (Note 3.2-1)
- The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by Good Display.
- Vcom value will be OTP before in factory or present on the label sticker.

Note 3.2-1
The Typical power consumption





3.3 Serial Peripheral Interface Timing

The following specifications apply for: VSS=0V, VCI=2.2V to 3.7V, T_{OPR} =25 $^{\circ}$ C

Write mode

| Symbol | Parameter | Min | Тур | Max | Unit |
|----------|--|-----|-----|-----|------|
| fSCL | SCL frequency (Write Mode) | | | 20 | MHz |
| tCSSU | Time CSB has to be low before the first rising edge of SCLK | 20 | | 4 | ns |
| tCSHLD | Time CSB has to remain low after the last falling edge of SCLK | 20 | | | ns |
| tCSHIGH | Time CSB has to remain high between two transfers | 100 | | | ns |
| tSCLHIGH | Part of the clock period where SCL has to remain high | 25 | | | ns |
| tSCLLOW | Part of the clock period where SCL has to remain low | 25 | | | ns |
| tSISU | Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL | 10 | | | ns |
| tSIHLD | Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL | 40 | | | ns |

Read mode

| Symbol | Parameter | Min | Тур | Max | Unit |
|----------|--|-----|-----|-----|------|
| fSCL | SCL frequency (Read Mode) | | | 2.5 | MHz |
| tCSSU | Time CSB has to be low before the first rising edge of SCLK | 100 | | | ns |
| tCSHLD | Time CSB has to remain low after the last falling edge of SCLK | 50 | | | ns |
| tCSHIGH | Time CSB has to remain high between two transfers | 250 | | | ns |
| tSCLHIGH | Part of the clock period where SCL has to remain high | 180 | | | ns |
| tSCLLOW | Part of the clock period where SCL has to remain low | 180 | | | ns |
| tSOSU | Time SO(SDA Read Mode) will be stable before the next rising edge of SCL | | 50 | | ns |
| tSOHLD | Time SO (SDA Read Mode) will remain stable after the falling edge of SCL | | 0 | | ns |

Note: All timings are based on 20% to 80% of VDDIO-VSS

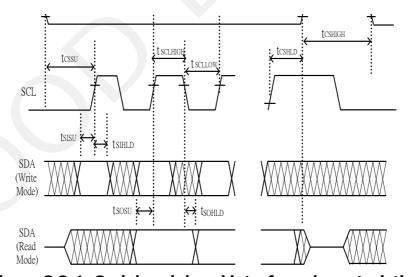


Figure 3.3-1: Serial peripheral interface characteristics

3.4 Power Consumption

| Parameter | Symbol | Conditions | TYP | Max | Unit | Remark |
|---------------------------------------|--------|------------|-----|-----|------|--------|
| Panel power consumption during update | - | 25℃ | | 75 | mAs | - |
| Deep sleep mode | - | 25℃ | | 2 | uA | - |

Mas=update average current × update time



3.5 MCU Interface

3.5.1 MCU interface selection

GDEH075T90 can support 4-wire or 3-wire serial peripheral MCU interface, which is pin selectable by BS1 pin. The interface pin assignment for different MCU interfaces is shown in Table 3.5-1.

Note

- (1) L is connected to VSS
- (2) H is connected to VDDIO

Table 3.5-1: Interface pin assignment for different MCU interfaces

| | | | | Pin Name | | | |
|---|-----|----------|----------|----------|-----|-----|-----|
| MCU Interface | BS1 | RES# | CS# | D/C# | SCL | SDI | SDO |
| 4-wire serial peripheral interface (SPI) | L | Required | Required | Required | SCL | SDI | SDO |
| 3-wire serial peripheral interface (SPI) – 9 bits SPI | Н | Required | Required | L | SCL | SDI | SDO |

3.5.2 MCU Serial Peripheral Interface (4-wire SPI)

The 4-wire SPI consists of serial clock SCL, serial data input SDI, D/C# and CS#. The control pins status in 4-wire SPI in writing command/data is shown in Table 3.5-2 and the write procedure in 4-wire SPI is shown in Figure 3.5-1..

Table 3.5-2: Control pins status of 4-wire SPI

| Function | SCL pin | SDI pin | D/C# pin | CS# pin |
|---------------|----------|-------------|----------|---------|
| Write command | 1 | Command bit | L | L |
| Write data | ↑ | Data bit | Н | L |



Note:

- (1) L is connected to VSS and H is connected to VDDIO
- (2) ↑ stands for rising edge of signal
- (3) SDI is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM (RAM)/Data Byte register or command Byte register according to D/C# pin.

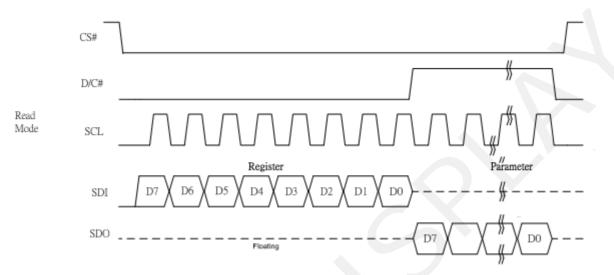


Figure 3.5-1: Read procedure in 4-wire SPI mode

In the read operation, after CS# is pulled low, the first byte sent is command byte, D/C# is pulled low. After command byte sent, the following byte(s) read are data byte(s), so D/C# bit is then pulled high. An 8-bit data will be shifted out on every clock falling edge. The serial data output SDO bit shifting sequence is D7, D6, to D0 bit. Figure 3.5-2 shows the read procedure in 4-wire SPI.

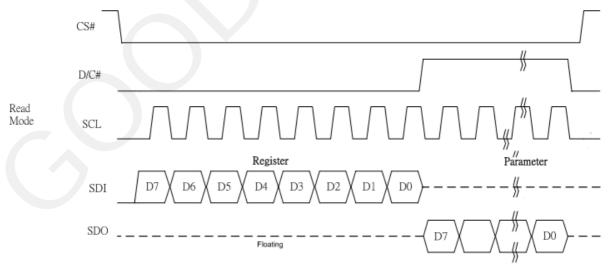


Figure 3.5-2: Read procedure in 4-wire SPI mode



3.5.3 MCU Serial Peripheral Interface (3-wire SPI)

The 3-wire SPI consists of serial clock SCL, serial data input SDI, and CS#. The operation is similar to 4- wire SPI while D/C# pin is not used and it must be tied to LOW. The control pins status in 3-wire SPI is shown in Table 3.5-3.

In the write operation, a 9-bit data will be shifted into the shift register on every clock rising edge. The bit shifting sequence is D/C# bit, D7 bit, D6 bit to D0 bit. The first bit is D/C# bit which determines the following byte is command or data. When D/C# bit is 0, the following byte is command. When D/C# bit is 1, the following byte is data. Table 3.5-3 shows the write procedure in 3-wire SPI

| | | - • | | |
|---------------|----------|-------------|----------|---------|
| Function | SCL pin | SDI pin | D/C# pin | CS# pin |
| Write command | ↑ | Command bit | Tie LOW | L |

Data bit

Tie LOW

Table 3.5-3: Control pins status of 3-wire SPI

Note:

Write data

- (1) L is connected to V_{SS} and H is connected to V_{DDIO}
- (2) ↑ stands for rising edge of signal

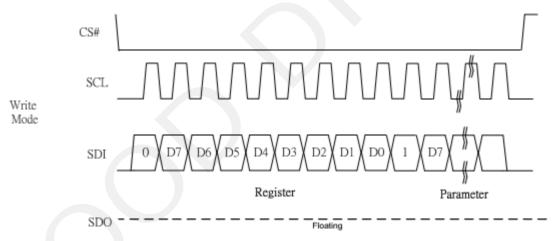


Figure 3.5-3: Write procedure in 3-wire SPI mode

In the read operation, serial data are transferred in the unit of 9 bits. After CS# pull low, the first byte is command byte, the D/C# bit is as 0 and following with the register byte. After command byte send, the following byte(s) are data byte(s), with D/C# bit is 1. After D/C# bit sending from MCU, an 8-bit data will be shifted out on every clock falling edge. The serial data output SDO bit shifting sequence is D7, D6, to D0 bit. Figure 7-4 shows the read procedure in 3-wire SPI.

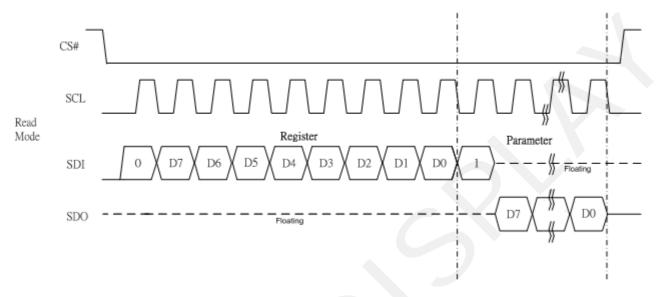
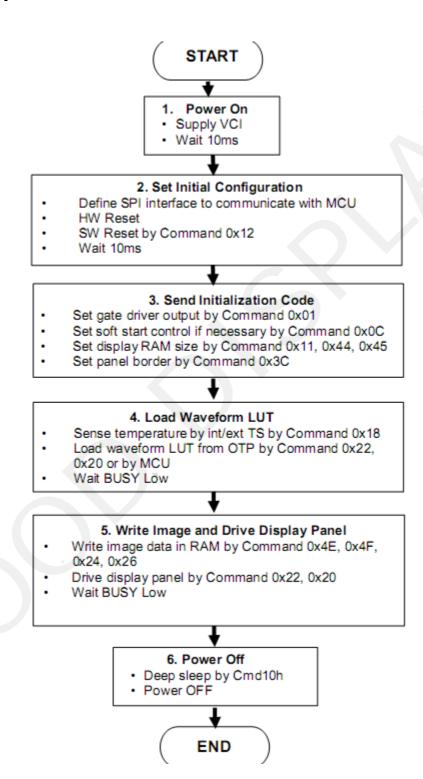


Figure 3.5-4: Read procedure in 3-wire SPI mode



4. Typical Operating Sequence

4.1 Normal Operation Flow





5. COMMAND TABLE

| Comma | nd Table | | | | | | | | | | | | | | |
|-------|----------|-----|----|----|----|----|----|----|----|----|---------------------------------|--|--|--|--------------------------------|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Descriptio | n | | |
|) | 0 | 01 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | Driver Output control | Gate settin | g A7h [POR], | 680 MIIV | |
|) | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | | | | ng as (A[9:0] |] + 1). |
|) | 1 | | 0 | 0 | 0 | 0 | 0 | 0 | A9 | A8 | | B[2:0] = 0 | 00 [POR]. | | |
|) | 1 | | 0 | | 0 | 0 | 0 | B2 | В1 | В0 | | | | ce and direct | tion |
| | | | | | | | | | | | | GD=0 [PC G0 is the 1 output seq GD=1, G1 is the 1 output seq B[1]: SM Change sc SM=0 [PC G0, G1, G interlaced) SM=1, G0, G2, G | st gate outpuence is G0 st gate outpuence is G1 anning orde DR], 2, G3679 4G678, G | out channel, ,G1, G2, G3 out channel, ,G0, G3, G2 or of gate driver (left and right G1, G3,G | gate 2, ver. ght gate |
| | | | | | | | | | | | | TB = 1, sc | an from G6 | /9 to G0. | |
|) | 0 | 03 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1 | Gate Driving voltage Control | A[4:0] = 0 | riving volta 0h [POR] ng from 12V | | |
| | | | | | | | | | | | | A[4:0] | VGH | A[4:0] | VGH |
| | | | | | | | | | | | | 00h | 20 | 10h | 16.5 |
| | | | | | | | | | | | | 07h | 12 | 11h | 17 |
| | | | | | | | | | | | | 08h | 12.5 | 12h | 17.5 |
| | | | | | | | | | | | | 09h | 13 | 13h | 18 |
| | | | | | | | | | | | | 0Ah | 13.5 | 14h | 18.5 |
| | | | | | | | | | | | | 0Bh | 14 | 15h | 19 |
| | | | | | | | | | | | | 0Ch | 14.5 | 16h | 19.5 |
| | | | | | | | | | | | | 0Dh | 15 | 17h | 20 |
| | | | | | | | | | | | | 0Eh | 15.5 | Other | NA |
| | | | | | | | | | | | | 0Fh | 16 | | |
| | | | | | | | 1 | | | | ĺ | | | - | |



| ommar /W# | D/O | | TT | D | D6 | D5 | D4 | D | D2 | | D1 | | D0 | Comn | 1 man | | Description | | |
|-----------------|--------|--------|----------|--------|--------|-----|-------|----------|-----|--------------|---------|---------|----------|----------|-------|-----------------------------|--------------------------|------------------------|--------------------------------|
| | | _# | Hex | 7 | | | | 3 | | | | | | | | . 1 | Descriptio | on | |
|) | 0 | | 04 | 0 | 0 | 0 | 0 | 0 | 1 | | 0 | | 0 | Contro | | ving voltage | Set Source | | |
|) | 1 | | | A 7 | A6 | A5 | A4 | A 3 | A2 | | A1 | | A2 | | | | A[7:0] = 4 B[7:0] = 4 | IIh [POR] Ash [POR] | , VSH1 at 15V , VSH2 at 5V. |
|) | 1 | | | В7 | В6 | B5 | B4 | В3 | В2 | | B1 | | В0 | | | | | | , VSL at -15V |
|) | 1 | | | C7 | C6 | C5 | C4 | C3 | C2 | | C1 | | C0 | | | | | | |
| 3[7] = 1 | | _ | | | | | | | A[7 | 7]/B[7] | = 0, | | | | | | C[7] = 0, | | |
| VSH2 vo 3.8V | oltage | settin | g from 2 | .4V to | | | | | | H1/VS 17V | H2 volt | age set | ting fro | om 9V | | | VSL settir | ng from -9 | V to -17V |
| A/B[| 7:0] | VSF | H1/VSH2 | 2 A/ | B[7:0] | VSH | 1/VSH | [2 | | A/B[7:0 |] VS | H1/VS | H2 | A/B[7:0] | V | SH1/VSH2 | | C[7:0] | VSL |
| 8Eh | | 2.4 | | AI | -Th | 5.7 | | | 2 | 3h | 9 | | | 3Ch | 14 | 1 | | 1Ah | -9 |
| 8Fh | | 2.5 | | В |)h | 5.8 | | | 2 | 4h | 9.2 | | | 3Dh | 14 | 1.2 | | 1Ch | -9.5 |
| 90h | | 2.6 | | B1 | h | 5.9 | | = | 2 | 5h | 9.4 | | | 3Eh | 14 | 1.4 | | 1Eh | -10 |
| 91h | | 2.7 | | B2 | 2h | 6 | | = | 2 | 6h | 9.6 | | | 3Fh | 14 | 1.6 | | 20h | -10.5 |
| 92h | | 2.8 | | В3 | | 6.1 | | \dashv | 2 | 7h | 9.8 | | 1 | 40h | 14 | 1.8 | | 22h | -11 |
| 93h | | 2.9 | | B4 | | 6.2 | | \dashv | 2 | 8h | 10 | | | 41h | 15 | 5 | | 24h | -11.5 |
| 94h | | 3 | | B5 | | 6.3 | | \dashv | 2 | 9h | 10. | 2 | | 42h | 15 | 5.2 | | 26h | -12 |
| 95h | | 3.1 | | B6 | | 6.4 | | \dashv | 2 | Ah | 10. | 4 | | 43h | 15 | 5.4 | | 28h | -12.5 |
| 96h | | 3.2 | | B7 | | 6.5 | | | 2 | Bh | 10. | 6 | | 44h | 15 | 5.6 | | 2Ah | -13 |
| 97h | | 3.3 | | B8 | | 6.6 | | | 2 | .Ch | 10. | 8 | | 45h | 15 | 5.8 | | 2Ch | -13.5 |
| 98h | | 3.4 | | B9 | | 6.7 | | | 2 | Dh | 11 | | | 46h | 16 | | | 2Eh | -14 |
| 99h | | 3.5 | | BA | | 6.8 | | | | Eh | 11. | | | 47h | | 5.2 | | 30h | -14.5 |
| 9Ah | | 3.6 | | BI | | 6.9 | | | | Fh | 11. | | | 48h | | 5.4 | | 32h | -15 |
| 9Bh | | 3.7 | | BO | | 7 | | | | 0h | 11. | | | 49h | | 5.6 | | 34h | -15.5 |
| 9Ch | | 3.8 | | BI | | 7.1 | | | | 1h | 11. | 8 | | 4Ah | | 5.8 | | 36h | -16 |
| 9Dh | | 3.9 | | BI | | 7.1 | | | | 2h | 12 | | | 4Bh | 17 | | | 38h | -16.5 |
| 9Eh | | 4 | | BI | | 7.3 | | | | 3h | 12. | | | Other | N | A | | 3Ah | -17 |
| 9Fh | | 4.1 | | CO | | 7.3 | | | | 4h | 12. | | | | | | | Other | NA |
| A0h | | 4.2 | | C1 | | 7.5 | | 4 | | 5h | 12. | | | | | | | | |
| Alh | | 4.2 | | C2 | | 7.6 | | | | 6h | 12. | 8 | | | | | | | |
| A2h | | 4.4 | | C2 | | 7.7 | | | | 7h | 13 | | | | | | | | |
| A3h | | 4.4 | | C4 | | 7.7 | | | | 8h | 13. | | | | | | | | |
| A4h | | 4.6 | | C4 | | 7.9 | _ | | | 9h | 13. | | | | | | | | |
| A4n A5h | | 4.6 | | Co | | 8 | | + | | Ah Bh | 13. | | | | | | | | |
| | | 4.7 | | C7 | | 8.1 | | Щ | 3 | DII | 13. | o . | | | | | | | |
| A6h | | | | | | 8.1 | | _ | | | | | | | | | | | |
| A7h | | 4.9 | | C8 | | | | _ | | | | | | | | | | | |
| A8h | | 5 | | C9 | | 8.3 | | _ | | | | | | | | | | | |
| A9h | | 5.1 | | CA | | 8.4 | | _ | | | | | | | | | Remark: | | |
| AAh | | 5.2 | | CI | | 8.5 | | _ | | | | | | | | | VSH1> V | SH2 | |
| ABh | | 5.3 | A | CC | | 8.6 | | _ | | | | | | | | | | | |
| ACh | | 5.4 | | CI | | 8.7 | | _ | | | | | | | | | | | |
| ADh | | 5.5 | | CI | | 8.8 | | _ | | | | | | | | | | | |
| AEh | | 5.6 | | | her | NA | | | | - | | | - | | | | | | |
|) | 0 | | 0F | 0 | 0 | 0 | 0 | 1 | | 1 | 1 | 1 | | e scan s | tart | Set the scan driver. The | | | |
|) | 1 | | | A7 | A6 | A5 | A4 | Α | | A2 | A1 | A0 | posi | LIUII | | A[9:0] = 00 | | 5 110111 U l | 0 0 / 7. |
| 0 | 1 | | | 0 | 0 | 0 | 0 | 0 | | 0 | A9 | A8 | | | | | | | |
| | | | | | | 1 | 1 | | | | | | | | | When TB=0 SCN [9:0] = | | | |
| | | | | | | 1 | 1 | | | | | | | | | SCN [9:0] = When TB=1 | | | |
| | | | | | | 1 | | | | | | | 1 | | | SCN [9:0] = | |)] | |



| Comman | d Table | | | | | | | | | | | |
|--------|---------|-----|-----|-----|-----|-----|-----|---------|------|---------|-------------------------|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description |
| 0 0 | 0 | 10 | 0 | 0 | 0 0 | 1 0 | 0 | 0 A2 | 0 A1 | 0 A0 | Deep Sleep mode | Deep Sleep mode Control: A[1:0]: Description 00 Normal Mode [POR] 01 Enter Deep Sleep Mode 1 11 Enter Deep Sleep Mode 2 After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high. Remark: To Exit Deep Sleep mode, User required |
| 0 0 | 0 1 | 11 | 0 0 | 0 0 | 0 0 | 1 0 | 0 0 | 0 A2 | 0 A1 | 1 A0 | Data Entry mode setting | Define data entry sequence A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 -Y decrement, X decrement, |
| | | | | | | | | | | | | 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction. |
| 0 | 0 | 12 | 0 | 0 | 0 | 1 | 0 | 0 | 1 | 0 | SW RESET | It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM are unaffected by this command. |



| Comma | ınd Table | | | | | | | | | | | |
|-------|-----------|-----|---------|---------|---------|---------|---------|---------|---------|---------|--|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description |
| 0 | 0 | 14 | 0 | 0 | 0 | 1 | 0 | 1 | 0 | 0 | HV Ready Detection | HV ready detection A[6:0] = 00h [POR] The command required CLKEN=1 and ANALOGEN=1. Refer to Register 0x22 for detail. After this command initiated, HV Ready detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F). |
| | | | | | | | | | | | | |
| 0 | 0 | 15 | 0 | 0 | 0 | 1 | 0 | 1 | 0 | 1 | VCI Detection | VCI Detection A[2:0] = 100 [POR], Detect level at 2.3V |
| 0 | 1 | | 0 | 0 | 0 | 0 | 0 | A2 | Al | A0 | | A[2:0] = 100 [POR], Detect level at 2.3V A[2:0] : VCI level Detect |
| | | | | | | | | | | | | A[2:0] VCI level |
| | | | | | | | | | | | | 011 2.2V |
| | | | | | | | | | | | | 100 2.3V 101 2.4V |
| | | | | | | | | | | | | 101 2.4V 110 2.5V |
| | | | | | | | | | | | | 111 2.6V |
| | | | | | | | | | | | | Other NA |
| | | | | | | | | | | | | The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, VCI detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F). |
| | | | | | | | | | | | | |
| 0 | 0 | 18 | 0 A7 | 0 A6 | 0 A5 | 1 A4 | 1 A3 | 0 A2 | 0 A1 | 0 A0 | Temperature Sensor Control | Temperature Sensor Selection A[7:0] = 48h [POR], external temperatrure sensor |
| U | 1 | | A/ | A0 | AS | A4 | AS | AZ | Al | AU | | A[7:0] = 80h Internal temperature sensor |
| | | | | | | | | | | | | |
| 0 | 0 | 1A | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0 | Temperature Sensor Control (Write to | Write to temperature register. A[11:0] = 7FFh[POR] |
| 0 | 1 | | A11 | A10 | A9 | A8 | A7 | A6 | A5 | A4 | temperature register) | |
| 0 | 1 | | A3 | A2 | A1 | A0 | 0 | 0 | 0 | 0 | | |
| | | | | 1 | | 1 | 1 | | 1 | | | 1 |
| 0 | 0 | 1B | 0 | 0 | 0 | 1 | 1 | 0 | 1 | 1 | Temperature Sensor Control (Read from | Read from temperature register. |
| 1 | 1 | | A11 | A10 | A9 | A8 | A7 | A6 | A5 | A4 | temperature register) | |
| 1 | 1 | | A3 | A2 | A1 | A0 | 0 | 0 | 0 | 0 | | |



| Comma | nd Table | | | | | | | | | | | | |
|-------|----------|-----|----------|----|----------|----------|----------|----------|----------|-----|---------------------------------------|---|------|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description | |
| 0 | 0 | 1C | 0 | 0 | 0 | 1 | 1 | 1 | 0 | 0 | Temperature Sensor | Write Command to External temperature | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | Control (Write Command to External | sensor. A[7:0] = 00h [POR], | |
| 0 | 1 | | B7 C7 | B6 | B5 C5 | B4 C4 | B3 C3 | B2 C2 | B1 C1 | B0 | | | |
| U | 1 | | C/ | C6 | CS | C4 | C3 | C2 | CI | C0 | temperature sensor) | B[7:0] = 00h [POR], C[7:0] = 00h [POR], | |
| | | | | | | | | | | | | A[7:6] | |
| | | | | | | | | | | | | A[7:6] Select no of byte to be sent 00 Address + pointer | |
| | | | | | | | | | | | | 01 Address + pointer + 1st aram | eter |
| | | | | | | | | | | | | 10 Address + pointer + 1st parameter +2nd pointer | |
| | | | | | | | | | | | | 11 Address | |
| | | | | | | | | | | | | A[5:0] – Pointer Setting B[7:0] – 1st parameter | |
| | | | | | | | | | | | | C[7:0] - 2nd parameter | |
| | | | | | | | | | | | | The command required CLKEN=1. Refer to Register 0x22 for detail. | |
| | | | | | | | | | | | | After this command initiated, Write | |
| | | | | | | | | | | | | Command to external temperature sensor starts. BUSY pad will output high during | |
| | | | | | | | | | | | | operation. | |
| 0 | 0 | 20 | 0 | 0 | l 1 | 0 | 0 | 0 | 0 | 0 . | Master Activation | Activate Display Update Sequence | |
| U | U | 20 | U | U | 1 | 0 | 0 | 0 | U | | Waster Activation | The Display Update Sequence Option is | |
| | | | | | | | | | | | | located at R22h. BUSY pad will output high during | |
| | | | | | | | | | | | | operation. User should not interrupt this | |
| | | | | | | | | | | | | operation to avoid corruption of panel images. | |
| | | I | | | | | | | | | | mages. | |
| 0 | 0 | 21 | 0 | 0 | 1 | 0 | 0 | 0 | 0 | 1 | Display Update | RAM content option for Display Update | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | Control 1 | A[7:0] = 00h [POR] A[7:4] Red RAM option | |
| | | | | | | | | | | | | 0000 Normal | |
| | | | | | | | | | | | | 0100 Bypass RAM content as 0 1000 Inverse RAM content | |
| | | | | | | | | | | | | A[3:0] BW RAM option | |
| | | | | | | | | | | | | 0000 Normal 0100 Bypass RAM content as 0 | |
| | | | | | | | | | | | | 1000 Inverse RAM content | |
| 0 | 0 | 22 | 0 | 0 | 1 | 0 | 0 | 0 | 1 | 0 | Display Update Control 2 | Display Update Sequence Option: Enable the stage for Master Activation | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | Control 2 | A[7:0]= FFh (POR) | |
| | | | | | | | | | | | | Parame | |
| | | | | | | | | | | | | Enable Clock Signal, (in H | ex) |
| | | | | | | | | | | | | Then Enable ANALOG | |
| | | | | | | | | | | | | Then DISPLAY with C7 | |
| | | | | | | | | | | | | DISPLAY Mode 1 Then Disable ANALOG | |
| | | | | | | | | | | | | Then Disable OSC | |
| | | | | | | | | | | | | Enable Clock Signal, Then Enable ANALOG | |
| | | | | | | | | | | | | Then DISPLAY with | |
| | | | | | | | | | | | | DISPLAY Mode 2 Then Disable ANALOG | |
| | | | | | | | | | | | | Then Disable ANALOG Then Disable OSC | |
| | | | | | | | | | | | | | |
| | | | | | | | | | | | | Enable Clock Signal, | |
| | | | | | | | | | | | | Then Load LUT with 90 | |
| | | | | | | | | | | | | DISPLAY Mode 1 | |
| | | | | | | | | | | | | Enable Clock Signal, Then Load Temperature | |
| | | | | | | | | | | | | value from I2C | |
| | | | | | | | | | | | | Single Master Interface | |
| | | | | | | | | | | | | Then Load LUT with DISPLAY Mode 1 | |



| | | Enable Clock Signal, Then Load LUT with DISPLAY Mode 2 Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 2 Enable Clock Signal, Then Load LUT with DISPLAY Mode 1 To Disable Clock Signal Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 1 To Disable Clock Signal Enable Clock Signal, Then Load LUT with DISPLAY Mode 2 To Disable Clock Signal Enable Clock Signal, Then Load Temperature value from I2C Single Master Interface Then Load Temperature value from I2C Single Master Interface Then Load Temperature value from I2C Single Master Interface Then Load LUT with DISPLAY Mode 2 To Disable Clock Signal Enable Clock Signal Enable ANALOG Then DISPLAY with DISPLAY Mode 1 Then Disable ANALOG Then DISPLAY with DISPLAY Mode 2 Then Disable ANALOG Then Disable OSC Enable ANALOG Then Disable ANALOG Then DispLAY with DISPLAY Mode 1 Enable ANALOG Then DISPLAY with DISPLAY Mode 1 Enable ANALOG Then DISPLAY with DISPLAY Mode 1 | 98 B8 91 B1 99 B9 47 4F 80 C0 44 4C 04 |
|--|--|--|--|
| | | Enable ANALOG Then DISPLAY with DISPLAY Mode 2 | 4C |
| | | | 0C |
| | | (CLKEN=0, ANALOGEN=0) o Disable Clock Signal (CLKEN=0) | 03 |



| Comma | nd Table | | | | | | | | | | | |
|-------|----------|-----|----|---------|----|----|-------------|---------|---------|---------|---------------------|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D 3 | D2 | D1 | D0 | Command | Description |
| 0 | 0 | 24 | 0 | 0 | 1 | 0 | 0 | 1 | 0 | 0 | Write RAM (BW) | After this command, data entries will be written into the BW RAM until another command is written. Address pointers will advance accordingly For Write pixel: Content of Write RAM(BW) = 1 For Black pixel: Content of Write RAM(BW) = 0 |
| 0 | 0 | 26 | 0 | 0 | 1 | 0 | 0 | 1 | 1 | 0 | Write RAM (RED) | After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly. For Red pixel: Content of Write RAM(RED) = 1 For non-Red pixel [Black or White]: Content of Write RAM(RED) = 0 |
| 0 | 0 | 27 | 0 | 0 | 1 | 0 | 0 | 1 | 1 | 1 | Read RAM | After this command, data read on the MCU bus will fetch data from RAM [According to parameter of Register 41h to select reading RAM(BW) / RAM(RED)], until another command is written. Address pointers will advance accordingly. The 1st byte of data read is dummy data. |
| 0 | 0 | 28 | 0 | 0 | 1 | 0 | 1 | 0 | 0 | 0 | VCOM Sense | Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. BUSY pad will output high during operation. |
| 0 | 0 | 29 | 0 | 0 A6 | 0 | 0 | 1 A 3 | 0 A2 | 0 A1 | 1 A0 | VCOM Sense Duration | Stabling time between entering VCOM sensing mode and reading acquired. A[6]=1, Normal Mode A[6]=0, Reserve A[3:0] = 09h, duration = 10s. VCOM sense duration = Setting + 1 Seconds |
| 0 | 0 | 2A | 0 | 0 | 1 | 0 | 1 | 0 | 1 | 0 | Program VCOM OTP | Program VCOM register into OTP The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation. |



| Comma | ınd Table | | | | | | | | | | | | | | |
|-------|-----------|-----|-----|----------|----|----------|----|----|----|----|---------------------|-------------------|-----------------------|---------------|--------------|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description | on | | |
| 0 | 0 | 2B | 0 | 0 | 1 | 0 | 1 | 0 | 1 | 1 | Write Register for | | mand is use | | |
| 0 | 1 | | 0 | 0 | 0 | 0 | 0 | 1 | 0 | 0 | VCOM Control | | VCOM tog D63h shou | | |
| 0 | 1 | | 0 | 1 | 1 | 0 | 0 | 0 | 1 | 1 | | command | | iiu be set i | or uns |
| | 1 | | | | | | l | | l | l | | | | | |
| 0 | 0 | 2C | 0 | 0 | 1 | 0 | 1 | 1 | 0 | 0 | Write VCOM register | | | r from MO | CU interface |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | | | 00h [POR] | A [7.0] | VCOM |
| | | | | | | | | | | | | A[7:0] 08h | VCOM -0.2 | A[7:0] 58h | VCOM -2.2 |
| | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | 0Ch | -0.3 | 5Ch | -2.3 |
| | | | | | | | | | | | | 10h | -0.4 | 60h | -2.4 |
| | | | | | | | | | | | | 14h | -0.5 | 64h | -2.5 |
| | | | | | | | | | | | | 18h | -0.6 | 68h | -2.6 |
| | | | | | | | | | | | | 1Ch | -0.7 | 6Ch | -2.7 |
| | | | | | | | | | | | | 20h 24h | -0.8 -0.9 | 70h 74h | -2.8 -2.9 |
| | | | | | | | | | | | | 24n 28h | -0.9 -1 | 74n 78h | -2.9 |
| | | | | | | | | | | | | 28n 2Ch | -1.1 | 78h | -3.1 |
| | | | | | | | | | | | | | | | -3.1 |
| | | | | | | | | | | | | 30h 34h | -1.2 -1.3 | 80h 84 | -3.2 |
| | | | | | | | | | | | | 34n 38h | -1.3 | 88 | -3.4 |
| | | | | | | | | | | | | 3Ch | -1.4 | 8C | -3.4 |
| | | | | | | | | | | | | 40h | -1.6 | 90 | -3.6 |
| | | | | | | | | | | | | 40h | -1.0 | 90 | -3.7 |
| | | | | | | | | | | | | 48h | -1.7 | 98 | -3.8 |
| | | | | | | | | | | | | 4Ch | -1.9 | 9C | -3.9 |
| | | | | | | | | | | | | 50h | -2 | A0 | -4 |
| | | | | | | | | | | | | 54h | -2.1 | Au | -4 |
| | | | | | | | | | | | | 3411 | -2.1 | | |
| 0 | 0 | 2D | 0 | 0 | 1 | 0 | 1 | 1 | 0 | 1 | OTP Register Read | Read Rea | ister for Di | snlav Onti | on. |
| 1 | 1 | 20 | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | forDisplay Option | A[7:0]: V | COM OTP | Selection | 011. |
| 1 | 1 | | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 | - | | nd 0x37, By | | |
| 1 | 1 | | C7 | C6 | C5 | C4 | C3 | C2 | C1 | C0 | - | (Comman | COM Registed (1920) | SICT | |
| 1 | 1 | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | | C[7:0]~G | [7:0]: Displ | | (0) |
| 1 | 1 | | E7 | E6 | E5 | E4 | E3 | E2 | E1 | E0 | 1 | (Comman [5 bytes] | d 0x37, By | te B to By | te G) |
| 1 | 1 | | F7 | F6 | F5 | F4 | F3 | F2 | F1 | F0 | 1 | H[7:0]~K | [7:0]: Wave | eform Vers | sion |
| 1 | 1 | | G7 | G6 | G5 | G4 | G3 | G2 | G1 | G0 | 1 | (Comman | d 0x37, By | te H to By | rte K) |
| 1 | 1 | | H7 | H6 | H5 | H4 | H3 | H2 | H1 | H0 | 1 | [4 bytes] | | | |
| 1 | 1 | | H / | 16 | I5 | H4 I4 | I3 | I2 | I1 | I0 | - | | | | |
| 1 | 1 | | | - | | - | | | | - | - | | | | |
| 1 | 1 | | J7 | J6 | J5 | J4 | J3 | J2 | J1 | J0 | - | | | | |
| 1 | 1 | | K7 | K6 | K5 | K4 | K3 | K2 | K1 | K0 | | | | | |



| Comma | ınd Table | ; | | | | | | | | | | | | | |
|-------|-----------|-----|----------|----------|----------|----------|----------|----------|----------|----------|-----------------------------------|--|--|--|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description | | | |
| 0 | 0 | 34 | 0 | 0 | 1 | 1 | 0 | 1 | 0 | 0 | CRC calculation | CRC calculation command for OTP content validation. BUSY pad will output high during operation. | | | |
| | | | | | | | | | | | | | | | |
| 0 | 0 | 35 | 0 | 0 | 1 | 1 | 0 | 1 | 0 | 1 | CRC Status Read | CRC Status Read A[15:0] is the CRC readout Value | | | |
| 1 | 1 | | A15 | A14 | A13 | A12 | A11 | A10 | A9 | A8 | | A[13.0] is the CRC readout value | | | |
| 1 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | | | | | |
| 0 | 0 | 36 | 0 | 0 | 1 | 1 | 0 | 1 | 1 | 0 | Program OTP selection | Program OTP Selection according to the OTP Selection Control [R37h and R38h] The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation. | | | |
| | I 0 | 27 | | 0 | 1 | 1 | 0 | 1 | 1 | 1 | l w/ i/ p · i / c | I W. A. D. L. O. C. | | | |
| 0 | 0 | 37 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | Write Register for Display Option | Write Register for Display Option B[7:0] Display Mode for WS[7:0] | | | |
| 0 | 1 | | | | | | | | | | | C[7:0] Display Mode for WS[15:8] | | | |
| 0 | 1 | | B7 | B6 | B5 | B4 | B3 | B2 | B1 | B0 | | D[7:0] Display Mode for WS[23:16] E[7:0] Display Mode for WS[31:24] F[3:0] Display Mode for WS[35:32] 0: Display Mode 1 1: Display Mode2 F[6]: PingPong for Display Mode 2 F[7]: PingPong for Display Mode 1 1: Ping-Pong | | | |
| 0 | 1 | | C7 | C6 | C5 | C4 | C3 | C2 | C1 | C0 | | | | | |
| 0 | 1 | | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | | | | | |
| 0 | 1 | | E7 | E6 | E5 | E4 | E3 | E2 | E1 | E0 | | | | | |
| 0 | 1 | | F7 G7 | F6 | F5 G5 | F4 G4 | F3 G3 | F2 G2 | F1 G1 | F0 G0 | | | | | |
| 0 | 1 | | H7 | G6 H6 | H5 | H4 | H3 | H2 | H1 | H0 | | 0: Default | | | |
| 0 | 1 | | I7 | I6 | I5 | I4 | I3 | I2 | II1 | I0 | | G[7:0]~J[7:0] module ID /waveform version. | | | |
| 0 | 1 | | J7 | J6 | J5 | J4 | J3 | J2 | J1 | J0 | | Remarks: A[7:0]~J[7:0] can be stored in | | | |
| | | | J , | | ,,, | <u> </u> | •5 | 32 | V 1 | | <u> </u> | OTP | | | |
| 0 | 0 | 38 | 0 | 0 | 1 | 1 | 1 | 0 | 0 | 0 | Write Register for | Write Register for User ID | | | |
| 0 | 1 | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | A7 | User ID | A[7:0]]~J[7:0]: UserID [10 bytes] Remarks: A[7:0]~J[7:0] can be stored in | | | |
| 0 | 1 | B7 | В6 | B5 | В4 | В3 | B2 | B1 | В0 | B7 | IIV | OTP | | | |
| 0 | 1 | C7 | C6 | C5 | C4 | C3 | C2 | C1 | C0 | C7 | | | | | |
| 0 | 1 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | D7 | | | | | |
| 0 | 1 | E7 | E6 | E5 | E4 | E3 | E2 | E1 | E0 | E7 | | | | | |
| 0 | 1 | F7 | F6 | F5 | F4 | F3 | F2 | F1 | F0 | F7 | | | | | |
| 0 | 1 | G7 | G6 | G5 | G4 | G3 | G2 | G1 | G0 | G7 | | | | | |
| 0 | 1 | Н7 | Н6 | H5 | H4 | НЗ | H2 | H1 | Н0 | H7 | | | | | |
| 0 | 1 | I7 | I6 | I5 | I4 | I3 | I2 | I1 | Ι0 | I7 | | | | | |
| 0 | 1 | J7 | J6 | J5 | J4 | Ј3 | J2 | J1 | J0 | J7 | | | | | |



| Comma | nd Table | | | | | | | | | | | | | |
|-------|----------|-----|---------|---------|------|------|---------|------|---------|---------|----------------------------|---|--|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description | | |
| 0 | 1 | 39 | 0 | 0 | 0 | 0 | 0 | 0 | 0 A1 | 1 A0 | OTP program mode | OTP program mode A[1:0] = 00: Normal Mode [POR] A[1:0] = 11: Internal generated OTP programming voltage Remark: User is required to EXACTLY follow the reference code sequences | | |
| | | | l | | | | | 1 | | 1 | | ronow the reference code sequences | | |
| 0 | 0 | 3A | 0 | 0 | 1 | 1 | 1 | 0 | 1 | 0 | Reserved | Reserved | | |
| | | | | | | | | | | | | | | |
| 0 | 0 | 3B | 0 | 0 | 1 | 1 | 1 | 0 | 1 | 1 | Reserved | Reserved | | |
| 0 | 0 | 3C | 0 A7 | 0 A6 | 1 A5 | 1 A4 | 1 A3 | 1 A2 | O A1 | 0 A0 | Border Waveform Control | Select border waveform for VBD | | |
| | | | | | | | | | | | | 10 LUT3 | | |
| 0 | 0 | 41 | 0 | 1 | 0 | 0 | 0 | 0 | 0 | 1 | Read RAM Option | Read RAM Option | | |
| 0 | 1 | | 0 | 0 | 0 | 0 | 0 | 0 | 0 | A0 | , op | A[0]= 0 [POR] 0: Read RAM corresponding to 24h 1: Read RAM corresponding to 26h | | |
| | 1 | | | | | | | | • | | | 1g | | |
| 0 | 0 | 44 | 0 | 1 | 0 | 0 | 0 | 1 | 0 | 0 | Set RAM X - address | Specify the start/end positions of the | | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | Start / End position | window address in the X direction by an address unit for RAM | | |
| 0 | 1 | | - | - | - | - | - | - | A9 | A8 | | A[9:0]: XSA[9:0], XStart, POR = 000h | | |
| 0 | 1 | | 0 | 0 | В5 | B4 | В3 | B2 | B1 | В0 | | B[5:0]: XEA[9:0], XEnd, POR = 3BFh | | |
| 0 | 1 | | - | - | - | - | - | - | В9 | В8 | | | | |



| Comma | ınd Table | | | | | | | | | | | |
|-------|-----------|-----|---------|----|----|----|----|----|----|----|--|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description |
| 0 | 0 | 45 | 0 | 1 | 0 | 0 | 0 | 1 | 0 | 1 | Set RAM Y- | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | address Start / End | Specify the start/end positions of the window address in the Y direction by an |
| 0 | 1 | | - | - | - | - | - | - | A9 | A8 | position | address unit for RAM |
| 0 | 1 | | В7 | В6 | B5 | B4 | В3 | B2 | B1 | В0 | | A[8:0]: YSA[8:0], YStart, POR = 000h B[8:0]: YEA[8:0], YEnd, POR = 2A7h |
| 0 | 1 | | - | - | - | - | - | - | В9 | В8 | | B[8:0]: YEA[8:0], YEND, POR = $2A/n$ |
| | | | | | | | | • | • | • | | |
| 0 | 0 | 46 | 0 | 1 | 0 | 0 | 0 | 1 | 1 | 0 | Auto Write RED | Auto Write RED RAM for Regular Pattern |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | Al | A0 | RAM for Regular Pattern | A[7:0] = 00h [POR] A[7]: The 1st step value, POR = 0 A[6:4]: Step Height, POR= 000 Step of alter RAM in Y-direction according to Gate A[6:4] |
| | | | | | | | | | | | , | |
| 0 | 0 | 47 | 0 | 1 | 0 | 0 | 0 | 1 | 1 | 1 | Auto Write B/W | Auto Write B/W RAM for Regular Pattern |
| 0 | 1 | 4/ | 0 A7 | A6 | A5 | A4 | A3 | A2 | Al | A0 | Auto Write B/W RAM for Regular Pattern | Auto Write B/W RAM for Regular Pattern A[7:0] = 00h [POR] Auto Write B/W RAM for Regular Pattern A[7:0] = 00h [POR] A[6:4] Height A[6:4] Height 000 8 100 128 001 16 101 256 010 32 110 512 011 64 111 960 A[2:0]: Step Width, POR= 000 Step of alter RAM in X-direction according to Source A[2:0] Width A[2:0] Width 000 8 100 128 001 16 101 256 010 32 110 512 011 64 111 680 uring operation, BUSY pad will output high. |



| Comma | and Table | ; | | | | | | | | | | | | |
|-------|-----------|-----|----|----|----|----|----|----|----|----|-----------|---|--|--|
| R/W# | D/C# | Hex | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 | Command | Description | | |
| 0 | 0 | 4E | 0 | 1 | 0 | 0 | 1 | 1 | 1 | 0 | Set RAM X | Make initial settings for the RAM X | | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | address | address in the address counter (AC) A[9:0]: 000h [POR]. | | |
| 0 | 1 | | 0 | 0 | 0 | 0 | 0 | 0 | A9 | A8 | counter | | | |
| | | | | | | | | | | | | | | |
| 0 | 0 | 4F | 0 | 1 | 0 | 0 | 1 | 1 | 1 | 1 | Set RAM Y | Make initial settings for the RAM Y | | |
| 0 | 1 | | A7 | A6 | A5 | A4 | A3 | A2 | A1 | A0 | address | address in the address counter (AC) | | |
| 0 | 1 | | 0 | 0 | 0 | 0 | 0 | 0 | A9 | A8 | counter | A[9:0]: 000h [POR]. | | |
| | _ | | | | | | | | | | | | | |
| 0 | 0 | 7F | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | NOP | This command is an empty command; it does not have any effect on the display module. However, it can be used to terminate Frame Memory Write or Read Commands. | | |



6. Optical characteristics

6.1 Specifications

Measurements are made with that the illumination is under an angle of 45 degrees, the detection is perpendicular unless otherwise specified.

T=25℃

| SYMBOL | PARAMETER | CONDITIO NS | MIN | ТҮРЕ | MAX | UNIT | Note |
|--------------|----------------|----------------|-----|-------------------|-----|------|------------|
| R | Reflectance | White | 30 | 35 | - | % | Note 6.1-1 |
| Gn | 2Grey Level | - | - | DS+(WS-DS)×n(m-1) | - | L* | - |
| CR | Contrast Ratio | indoor | - | 10 | - | - | _ |
| Panel's life | - | 0℃~30℃ | | 5years | - | - | Note 6.1-2 |

M:2

WS: White state, DS: Dark state

Note 6.1-1: Luminance meter: Eye - One Pro Spectrophotometer;

Note 6.1-2: We guarantee display quality from $0^{\circ} \text{C} \sim 30^{\circ} \text{C}$ generally,If operation ambient temperature from $0^{\circ} \text{50}^{\circ} \text{C}$, will Offer special waveform by Good Display.

We don't guarantee 5 years pixels display quality for humidity below 45%RH or above 70%RH:

Suggest Updated once a day;

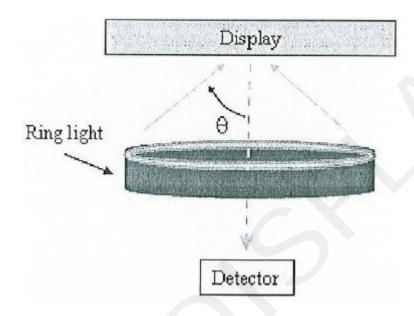


6.2 Definition of contrast ratio

The contrast ratio (CR) is the ratio between the reflectance in a full white area (R1) and the reflectance in a dark area (Rd)():

R1: white reflectance Rd: dark reflectance

CR = R1/Rd

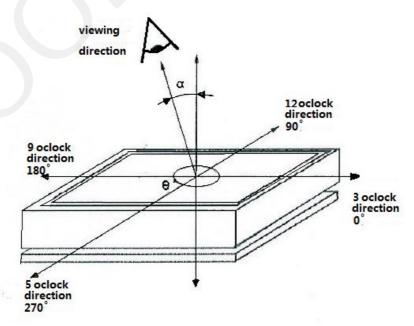


6.3 Reflection Ratio

The reflection ratio is expressed as:

 $R = Reflectance Factor_{white board} x (L_{center} / L_{white board})$

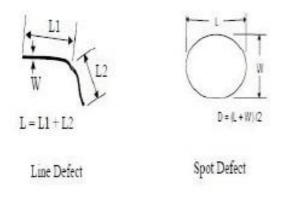
L $_{center}$ is the luminance measured at center in a white area (R=G=B=1) . L $_{white\ board}$ is the luminance of a standard white board . Both are measured with equivalent illumination source . The viewing angle shall be no more than 2 degrees .





7. Point and line standard

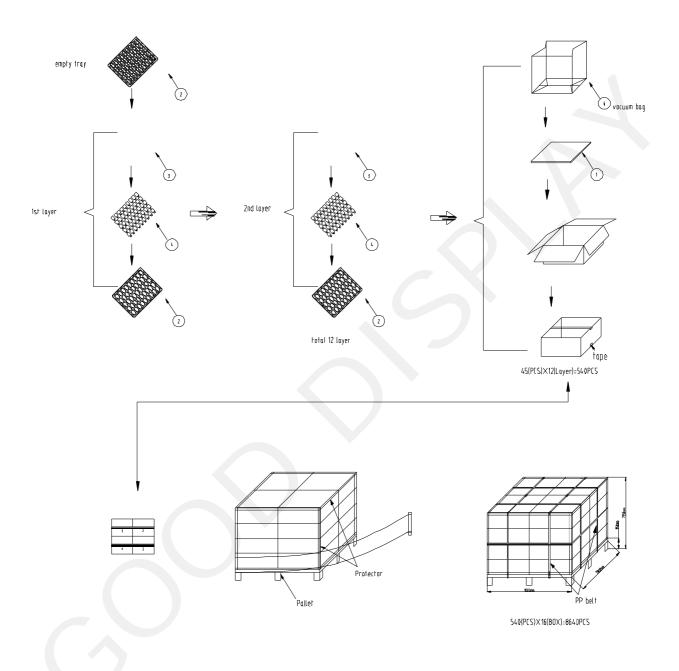
| | | Shipment Ins | spection Standard | | | | | | | | | |
|--|--|--|---|---------------|-----------|-------------|--|--|--|--|--|--|
| | Eq | uipment: Electri | cal test fixture, Point gaug | e | 1 | | | | | | | |
| Outline dimension | 170.2(H) × 111.2(V) ×1.25(D) | Unit: mm | Part-A | Active area | Part-B | Border area | | | | | | |
| | Temperature | Humidity | Illuminance | Distance Time | | Angle | | | | | | |
| Environment | 19℃~25℃ | 55%±5%RH | 800~1300Lux | 300 mm | 35Sec | | | | | | | |
| Defet type | Inspection method | | Standard | Part- | A | Part-B | | | | | | |
| | | I | O≤0.2 mm | Ignor | Ignore | | | | | | | |
| G 4 | Electric Discola | 0.2 m | m <d≤0.4 mm<="" td=""><td>N≤</td><td>Ignore</td></d≤0.4> | N≤ | Ignore | | | | | | | |
| Spot | Electric Display | 0.4 m | $m < D \le 0.6 \text{ mm}$ | N≤ | Ignore | | | | | | | |
| | | I | O>0.6 mm | Not Al | Ignore | | | | | | | |
| Display unwork | Electric Display | 1 | Not Allow | Not Al | Ignore | | | | | | | |
| Display error | Electric Display | 1 | Not Allow | Not Al | Ignore | | | | | | | |
| Scratch or line | | L≤2 r | nm, W≤0.1 mm | Ignoi | Ignore | | | | | | | |
| defect(include | Visual/Film card | 1.0mm <l≤9.0< td=""><td>0mm, 0.1<w≤0.2mm,< td=""><td>N≤</td><td colspan="3">N≤2</td></w≤0.2mm,<></td></l≤9.0<> | 0mm, 0.1 <w≤0.2mm,< td=""><td>N≤</td><td colspan="3">N≤2</td></w≤0.2mm,<> | N≤ | N≤2 | | | | | | | |
| Scratch or line defect(include dirt) | | L>9.0 | mm, W>0.2 mm | Not Al | Not Allow | | | | | | | |
| | | I | O≤0.4mm | Igno | re | Ignore | | | | | | |
| PS Bubble | Visual/Film card | 0.4m | m≤D≤0.6mm | N <u><</u> | Ignore | | | | | | | |
| | | Γ | Standard Part-A D \leq 0.2 mm Ignore 0.2 mm $<$ D \leq 0.4 mm N \leq 4 0.4 mm $<$ D \leq 0.6 mm Not Allow D \leq 0.4 mm Ignore 0.4 mm \leq D \leq 0.6 mm Not Allow D \leq 0.4 mm Ignore 0.4 mm \leq D \leq 0.6 mm Not Allow not affect the electrode circuit ((Corner chipping)) 8 mm, Y \leq 1 mm, Do not affect the electrode circuit, ore | low | Ignore | | | | | | | |
| Side Fragment | Visual/Film card | Do not affect the electrode circuit ((Corner chipping) X≤8mm, Y≤1mm, Do not affect the electrode circuit, Ignore | | | | | | | | | | |
| | 1.Cannot be defect & failure cause by appearance defect; | | | | | | | | | | | |
| Remark | 2.Cannot be larger size cause by appearance defect; | | | | | | | | | | | |
| | L=long W=wide D=point size N=Defects NO | | | | | | | | | | | |



L=long W=wide D=point size



8. Packing





9. Precautions

- (1) Do not apply pressure to the EPD panel in order to prevent damaging it.
- (2) Do not connect or disconnect the interface connector while the EPD panel is in operation.
- (3) Do not touch IC bonding area. It may scratch TFT lead or damage IC function.
- (4) Please be mindful of moisture to avoid its penetration into the EPD panel, which may cause damage during operation.
- (5) If the EPD Panel / Module is not refreshed every 24 hours, a phenomena known as "Ghosting" or "Image Sticking" may occur. It is recommended to refreshed the ESL /EPD Tag every 24 hours in use case. It is recommended that customer ships or stores the ESL / EPD Tag with a completely white image to avoid this issue
- (6) High temperature, high humidity, sunlight or fluorescent light may degrade the EPD panel's performance. Please do not expose the unprotected EPD panel to high temperature, high humidity, sunlight, or fluorescent for long periods of time.
- (7) For more precautions, please click on the link: http://www.e-paper-display.com/news_detail/newsId=53.html